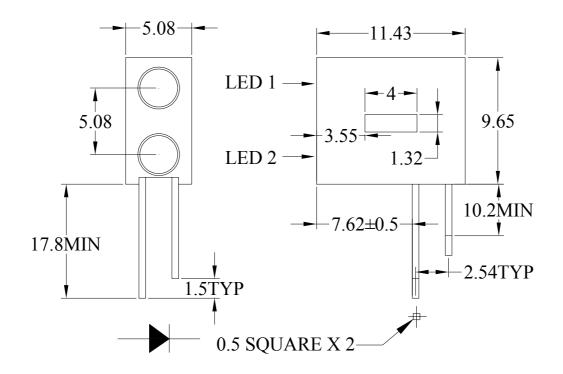
SPECIFICATION

PART NO. : LT632G-H203 2.9mm ROUND LED LAMP WITH HOLDER



Approved by	Checked by	Prepared by		
SAN	Sunny	Angel		

Package Dimensions



Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.25 mm unless otherwise noted.
- 3. The color of holder: Black.

Description

Part No.	LED Chip			
	Material	Emitting Color	Description	
LT632G-H203	GaP/GaP	Green	Green Diffused	

REV.: 01 Date: 2005.12.02 Page: 1/4

Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	78	mW
Reverse Voltage	VR	5	V
D.C. Forward Current	If	30	mA
Peak Current(1/10Duty duty,0.1ms Pulse Width.)	If(Peak)	100	mA
Operating Temperature Range	Topr.	-25 to +85	$^{\circ}$
Storage Temperature Range	Tstg.	-40 to +100	$^{\circ}\!\mathbb{C}$

Electrical and Optical Characteristics:

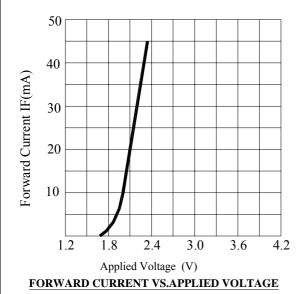
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	Iv	If=20mA	11.0	18.0		mcd
Forward Voltage	Vf	If=20mA		2.1	2.6	V
Peak Wavelength	λΡ	If=20mA		567		nm
Dominant Wavelength	λD	If=20mA		572		nm
Reverse Current	Ir	Vr=5V			100	μΑ
Viewing Angle	2 0 1/2	If=20mA		55		deg
Spectrum Line Halfwidth	Δλ	If=20mA		30		nm

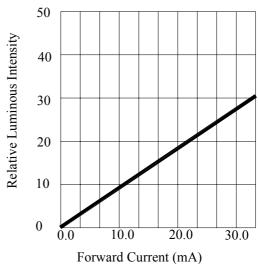
NOTE: THE DATAS COME FROM THE SPEC. OF LT6321-41

REV.: 01 Date: 2005.12.02 Page: 2/4

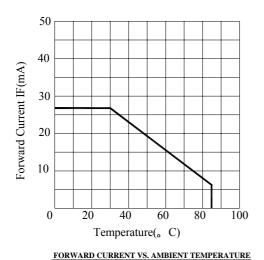
Typical Electrical/Optical Characteristic Curves

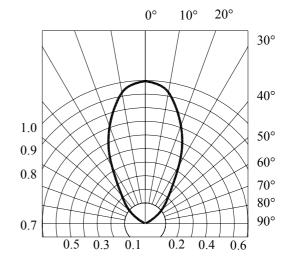
(25°C Ambient Temperature Unless Otherwise Noted)





FORWARD CURRENT VS. LUMINOUS INTENSITY





RADIATION DIAGRAM

REV.: 01 Date: 2005.12.02 Page: 3/4

Precautions in Use:

Storage

Recommend storage environment

Temperature: $5 \sim 30$

Soldering

Reflow Soldering

Recommend use of upper and lower heater type reflow furnace.

300°C Max for up to 5 seconds.

Pre-heat is 150°C Max for up to 2 minutes Max.

In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

Manual Iron Soldering (NOT RECOMMENDED)

Use SN60 solder of solder with silver content.

Use 25W soldering iron at 300°C Max for 5 seconds or less.

Must not touch top resin portion of lamp by heated soldering iron.

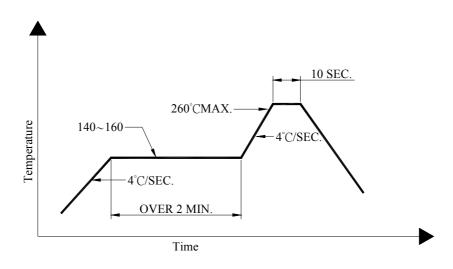
Cleaning

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

Reflow Temp/Time:



REV.: 01 Date: 2005.12.02 Page: 4/4